PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Choon Meng CHUA	10/03/2007
Jacob Chee Hong PHANG	10/03/2007
Soon Huat TAN	10/03/2007
Lian Ser KOH	10/03/2007

RECEIVING PARTY DATA

Name:	SEMICAPS Pte Ltd	
Street Address:	28 Ayer Rajah Crescent #03-01	
City:	SINGAPORE	
State/Country:	SINGAPORE	
Postal Code:	139959	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11935401

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 4276-116

NAME OF SUBMITTER: Steven J. Hultquist

Total Attachments: 1

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REEL: 020071 FRAME: 0576

-OP \$40,00 1193

ASSIGNMENT

We, CHUA CHOON MENG, JACOB PHANG CHEE HONG, TAN SOON HUAT, and KOH LIAN SER have made an invention the specification of which is described in the U.S. patent application filed herewith in the United States Patent and Trademark Office entitled:

"METHOD OF TESTING AN ELECTRONIC CIRCUIT AND APPARATUS THEREOF"

We hereby assign to SEMICAPS Pte Ltd, 28 Ayer Rajah Crescent #03-01, Singapore 139959, all ownership and rights in:

- (i) the invention and U.S. Patent Application;
- non-provisional, continuing, divisional and continuation-in-part applications based on (ii) and claiming benefit and/or priority of said U.S. Patent Application;
- (iii) U.S. Patents on the invention; and
- corresponding foreign patent applications and patents. (iv)

We are making this assignment based on our employment relationship with SEMICAPS Pte Ltd.

We respectfully request the Commissioner for Patents of the United States and the appropriate officers of all foreign countries to issue patents on the invention to:

SEMICAPS Pte Ltd.

as owners of the invention and aforementioned patent rights.

We agree to execute any other legal documents that may be required to effectuate this Assignment.

We agree that we will promptly communicate to SEMICAPS all facts which come to our attention affecting the invention or patent rights.

We agree that we will testify in any interference or litigation involving the invention or patent rights.

We declare that we have not done anything in conflict with this Assignment.

Date 3001 2007 HANG CHEE HONG Date 3 of 2007 Date [2][1] . 3 00 2007 KOH LIAN SER Date

RECORDED: 11/06/2007

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REEL: 020071 FRAME: 0577